National Semiconductor

August 1995

74F125
Quad Buffer (TRI-STATE®)

Features

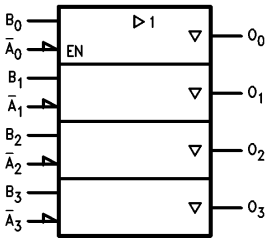
■ High impedance base inputs for reduced loading

Commercial	Package Number	Package Description
74F125PC	N14A	14-Lead (0.300″ Wide) Molded Dual-In-Line
74F125SC (Note 1)	M14A	14-Lead (0.150″ Wide) Molded Small Outline, JEDEC
74F125SJ (Note 1)	M14D	14-Lead (0.300″ Wide) Molded Small Outline, EIAJ

Note 1: Devices also available in 13″ reel. Use suffix = SCX and SJX.

Logic Symbol

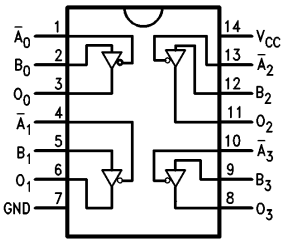
IEEE/IEC



TL/F/9475–4

Connection Diagram

Pin Assignment for SOIC and DIP



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Unit Loading/Fan Out

Pin Names	Description	74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
$\overline{A}_n$, B_n	Inputs	1.0/0.033	20 μA/−20 μA
O_n	Outputs	600/106.6 (80)	−12 mA/64 mA (48 mA)

Function Table

Inputs		Output
$\overline{A}_n$	B_n	O
L	L	L
L	H	H
H	X	Z

H = High Voltage Level
L = LOW Voltage Level
Z = High Impedance
X = Immaterial

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Absolute Maximum Ratings (Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
TRI-STATE Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I_{OL} (mA)

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Commercial	0°C to +70°C
Supply Voltage	
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

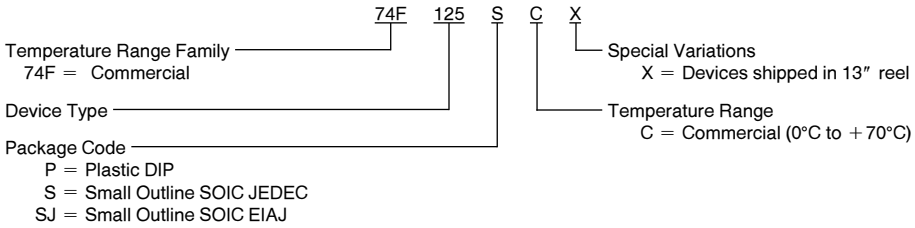
Symbol	Parameter		74F			Units	V_{CC}	Conditions
			Min	Typ	Max			
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	74F 10% V_{CC}	2.4			V	Min	I_{OH} = −3 mA
		74F 10% V_{CC}	2.0					I_{OH} = −12 mA
		74F 5% V_{CC}	2.7					I_{OH} = −3 mA
		74F 5% V_{CC}	2.0					I_{OH} = −15 mA
V_{OL}	Output LOW Voltage	74F 10% V_{CC}			0.55	V	Min	I_{OL} = 64 mA
I_{IH}	Input HIGH Current				20	μA	Max	V_{IN} = 2.7V
I_{BVI}	Input HIGH Current Breakdown Test				100	μA	0.0V	V_{IN} = 7.0V
I_{IL}	Input LOW Current				−20.0	μA	Max	V_{IN} = 0.5V
I_{OZH}	Output Leakage Current				50	μA	Max	V_{OUT} = 2.7V
I_{OZL}	Output Leakage Current				−50	μA	Max	V_{OUT} = 0.5V
I_{OS}	Output Short-Circuit Current		−100		−225	mA	Max	V_{OUT} = 0V
I_{CEX}	Output HIGH Leakage Current				250	μA	Max	V_{OUT} = V_{CC}
I_{ZZ}	Buss Drainage Test				500	μA	0.0V	V_{OUT} = 5.25V
I_{CCH}	Power Supply Current			18.5	24.0	mA	Max	V_O = HIGH
I_{CCL}	Power Supply Current			31.7	40.0	mA	Max	V_O = LOW
I_{CCZ}	Power Supply Current			27.6	35.0	mA	Max	V_O = HIGH Z

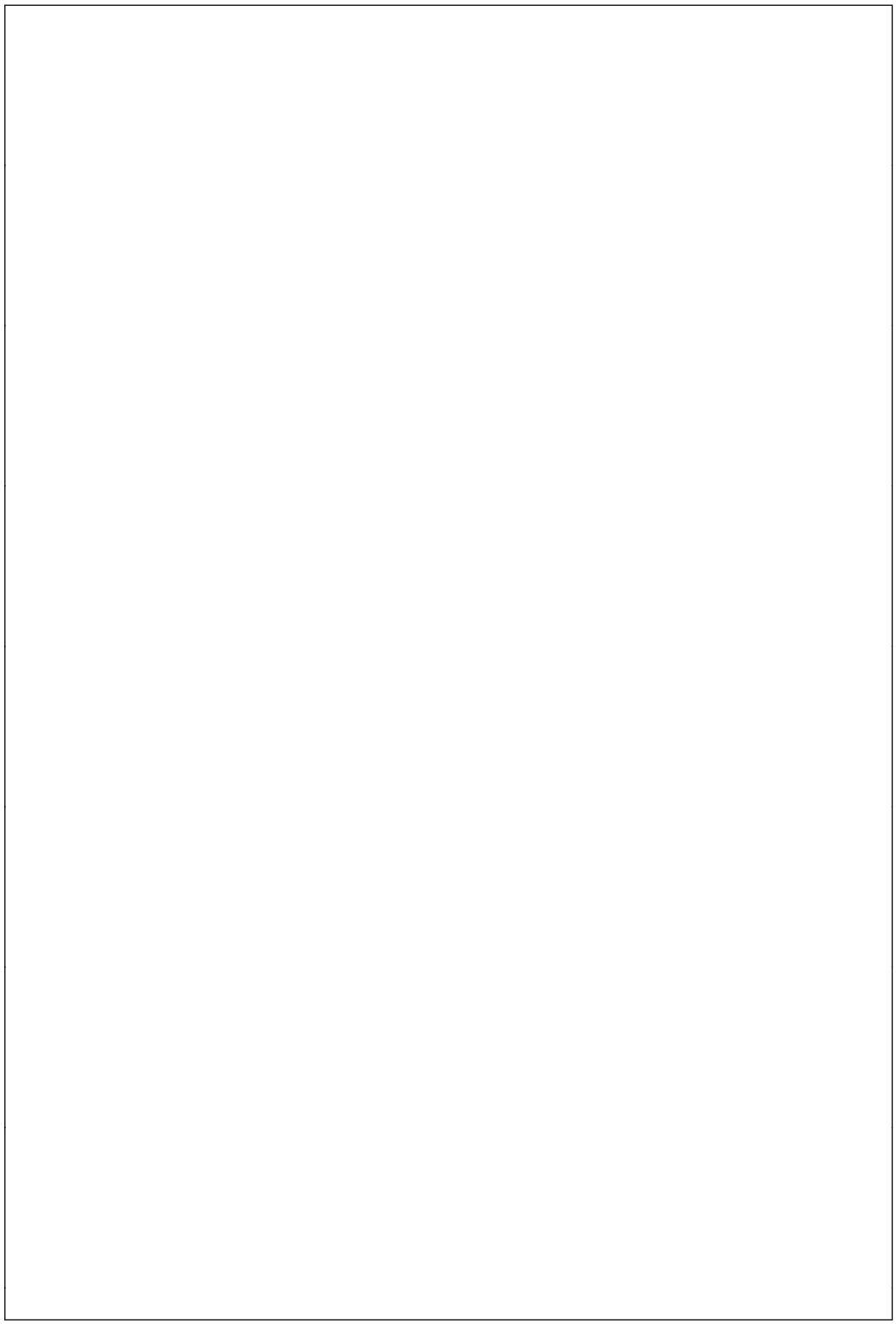
AC Electrical Characteristics

Symbol	Parameter	74F $T_A = +25°C$, $V_{CC} = +5.0V$, $C_L = 50$ pF			74F T_A, V_{CC} = Com, $C_L = 50$ pF		Units
		Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	2.0	4.0	6.0	2.0	6.5	ns
t_{PHL}		3.0	4.6	7.5	3.0	8.0	
t_{PZH}	Output Enable Time	3.5	4.7	7.5	3.0	8.5	ns
t_{PZL}		3.5	5.3	8.0	3.5	9.0	
t_{PHZ}	Output Disable Time	1.5	3.9	5.5	1.5	6.0	ns
t_{PLZ}		1.5	4.0	6.0	1.5	6.5	

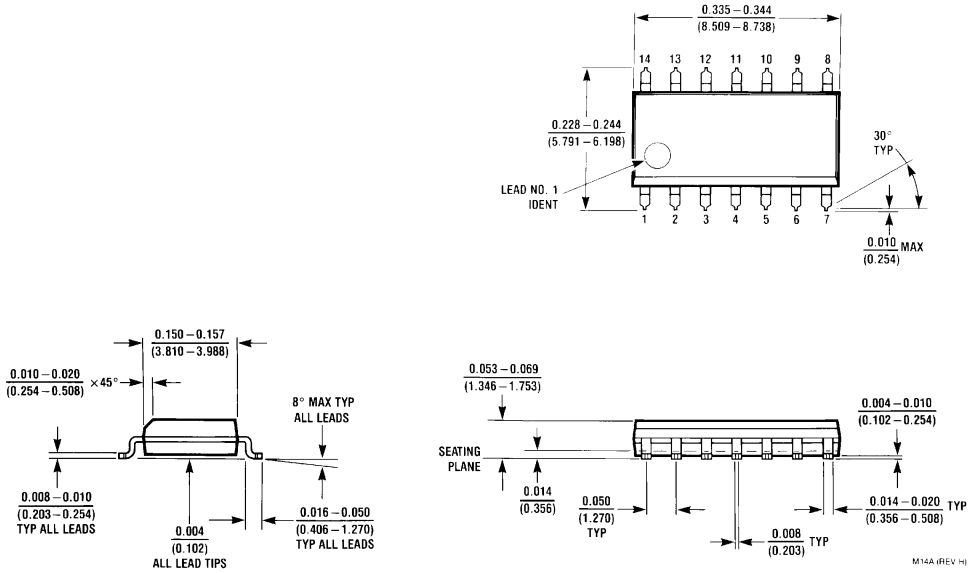
Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:

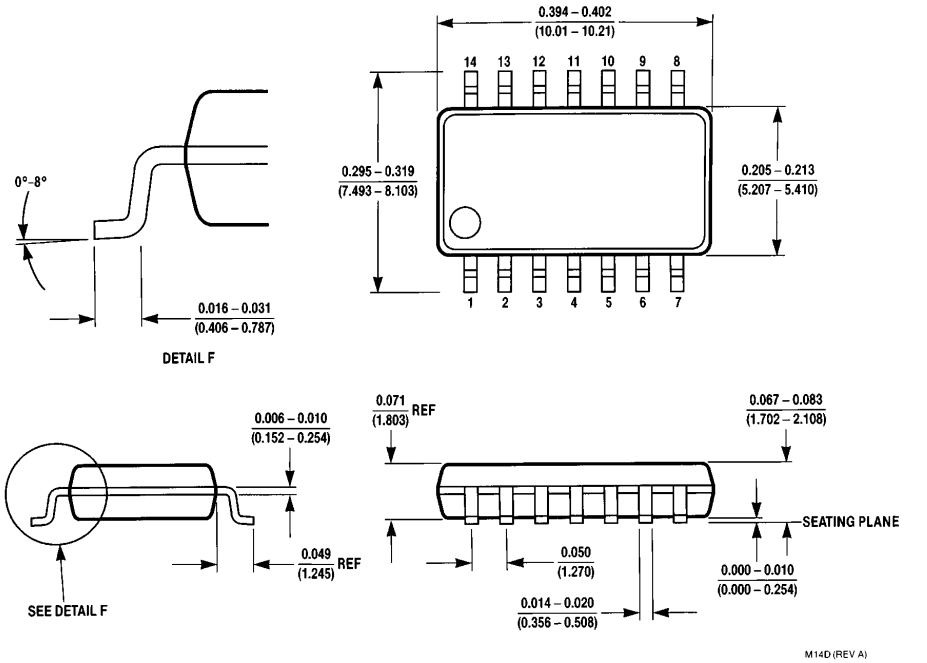




Physical Dimensions inches (millimeters)

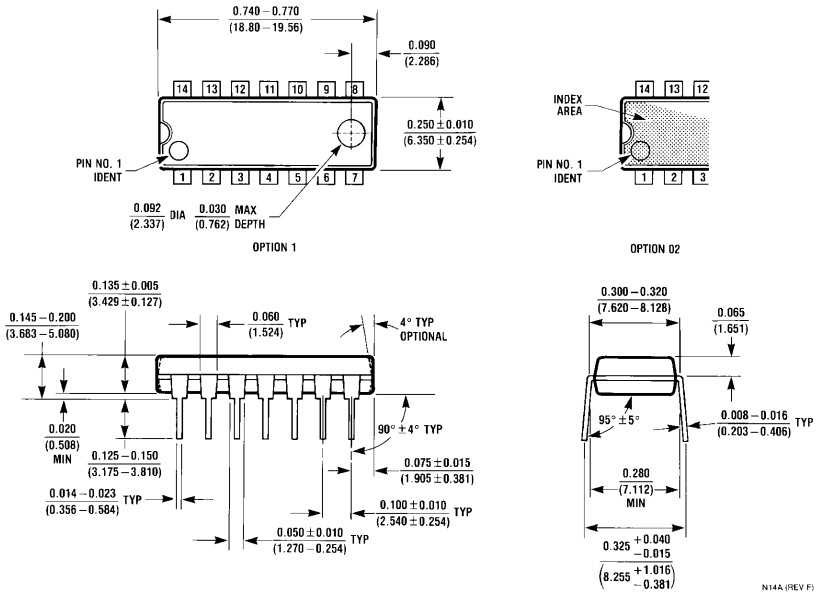


14-Lead (0.150″ Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M14A



14-Lead (0.300″ Wide) Molded Small Outline Package, EIAJ (SJ)
NS Package Number M14D

Physical Dimensions inches (millimeters) (Continued)



14-Lead (0.300″ Wide) Molded Dual-In-Line Package (P)
NS Package Number N14A

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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